

ABSTRACT

To provide a curable composition from which a cured film having lipophilicity to such an extent that application of an organic solvent-based coating liquid is possible while maintaining water repellency, having sufficient insulating properties and having a low dielectric constant, is obtained, a method for producing a cured film using the curable composition, and a semiconductor device using a cured film obtained by curing the curable composition.

A curable composition comprising a fluorinated polyarylene prepolymer (A) having crosslinkable functional groups, a compound (B) having at least two crosslinkable functional groups, having no fluorine atom and having a number average molecular weight of from 140 to 3,000, a compound (C) having a C₆₋₂₄ alkyl group which may have an etheric oxygen atom between carbon atoms, having crosslinkable functional groups, having no fluorine atom and having a number average molecular weight higher than 3,000 and at most 50,000, and a radical polymerization initiator (D).